

Late News Call for Papers Important Dates

Late News Submission deadline: June 1, 2021; Notification of acceptance: July 1, 2021 Video Presentation upload deadline: August 1, 2021 Early Bird Registration Deadline: June 30, 2021

IFETC, started in Ottawa, Canada (2018) is a new EDS-lead international conference, focusing upon printed and flexible hybrid and non-hybrid materials, devices and systems. It will rotate between the Americas, Asia and Europe, heading to Shanghai PRC in 2022. IFETC aims to bring together a wide variety of stakeholders, from chemists, materials scientists, polymer physicists, to mechanical and electrical engineers, the fabrication and manufacturing communities, as well as end-users, e.g. packaging and medical communities. We cordially invite your submissions.

Logistics:

- 100% Online Virtual
- New reduced pricing!



Important Features:

- Sunday (Aug. 8): Virtual Short Courses
- Monday (Aug 9): Plenary talks; IFETC Poster judging session with awards (1st, 2nd, 3rd)
- Tuesday (Aug 10): Plenary talks
- Wednesday (Aug 11): Plenary talks; Manufacturing & Workforce Panel
- Medical Wearable and Clinical Usage Panel
- Proceedings in IEEE Xplore; Selected papers in <u>IEEE J-EDS</u> or the newly created IEEE Journal of Flexible Electronics (J-FE).

All accepted papers presented at the conference will be published in the IFETC2021 proceedings and available on IEEE Xplore. Besides, the authors of selected high quality presented papers will be invited to submit an extended version of the same for consideration of publication in the IEEE Journal of Electron Devices Society (J-EDS) or the new IEEE Journal of Flexible Electronics (J-FE). All such submissions must comply with IEEE author-guidelines and be subjected to the standard IEEE and J-EDS /J-FE publication policies.



Full Sponsor



Technical Co-Sponsors



IEEE INSTRUMENTATION & MEASUREMENT INTITUTION SOCIETY®



Financial Co-Sponsors





Conference Topics:

- Materials:
 - Advanced Materials for Active Devices
 - Novel Materials and Stretchable Conductors
 - Low Temperature Processing
- Devices:
 - Liquid Electronics
 - Flexible IoT Sensors
 - Flexible Bio-medical Sensors
 - Flexible Thin Film Transistors
 - Energy Devices:
 - Flexible Photovoltaics
 - Flexible Energy Harvesting (RF, Heat, Motion, etc.)
 - Flexible Lighting and Displays
 - Flexible Batteries and Supercapacitors
 - RF Components:
 - Flexible RF Components / Connectors, RFID & NFC
 - Flexible Microwave Devices
 - Flexible Antennas
 - Systems:
 - Circuit Design for Flexible Electronics
 - Flexible Printed Electronics
 - Flexible Electronics for Robotics
 - Low Cost Flexible Electronics
 - Al/Machine Learning
 - Bio-Systems:
 - Wearable Devices and Electronic Textiles
 - Human/Machine (Skin/Electronic)
 - Medical School Roundtable
 - Back-End Processing:
 - Microelectronics Integration/Heterogeneous Integration
 - Flexible Hybrid Electronics (FHE) Manufacturing
 - Packaging





Organizing Committees:

- General Chair:
 - Paul R. Berger, Ohio State & Tampere University
- Technical Co-Chairs:
 - ◊ John Anthony, Kentucky
 - ◊ Luisa Petti, Bozen-Bolzano
 - ◊ Giorgio Bazzan, AFRL/NextFlex

• Treasurer:

- Massood Z. Atashbar (Western Michigan)
- Corporate Outreach Chair:

 Niels Benson (U-Duisburg Essen)
- Local Arrangements Chair:
 - Savas Kaya (Ohio U.)

International Advisory Committee:

- ◊ Paul Blom (MPI-Polymers, Mainz)
- ◊ Jean-Luc Brédas (Arizona)
- ◊ Stephen Forrest (Michigan)
- Richard Friend (Cambridge)
- ◊ Takao Someya (Tokyo)

Steering Committee:

- Ta-Ya Chu (NRC, Canada) Chair, EDS Flexible Electronics and Displays Committee
- Xiaojun Guo (Shanghai Jiao Tong University, P.R. China) - IFETC 2022 Program Chair
- Kazunari Ishimaru (Kioxia, Japan) Chair, Steering Comm.; EDS VP of Meetings & Conferences
- Samar K. Saha (Prospicient Devices, USA), EDS Sr. Past President
- Ravi Todi (Western Digital, USA) EDS President



Conference Committee:

- John Anthony (Kentucky) Organic Synthesis
- Massood Z. Atashbar (Western Michigan) Flexible
 Batteries
- C. Daniel Frisbie (Minnesota) Organic Electronics
- Samson A. Jenekhe (Washington) Semiconducting Polymers
- Savas Kaya (Ohio Univ.) Wearable Supercapacitors
- Eric MacDonald (Texas @ El Paso) Additive Printing
- Matti Mäntysalo (Tampere) Hybrid Integration
- Luisa Petti (Bozen-Bolzano) Flexible Devices
- Henning Sirringhaus (Cambridge) Transport/Devices
- Luisa Torsi (Bari Aldo Moro) Bioelectronics
- George Xiao (Canada NRC) RFID/Smart Textiles
- Peide Ye (Purdue) ALD and advanced processing

Virtual Short Courses

(Sunday, August 8, 2021):

- Additive Manufacturing
- Printed Electronics for Automotive Applications
- Flextronics: A Hard Barrier for Flexible Teaching?
- Printed Electronics Materials, Processes and Devices

